



MLCAD 2025

Call for Contributions

ACM/IEEE International Symposium on Machine Learning for CAD
September 8-10, 2025
Chaminade Resort, Santa Cruz, California

MLCAD Symposium (<https://mlcad.org/>)

The symposium focuses on Machine Learning (ML) applications to all aspects of CAD for electronic circuits, chips and systems. It is sponsored by IEEE CEDA (Council on Electronic Design Automation) and ACM SIGDA (Special Interest Group on Design Automation). MLCAD 2025 will start with the welcome reception in the evening of September 7, 2025. Papers and presentations should cover one or more aspects of applying machine learning and AI to enhance CAD of chip designs. Such aspects include, but are not limited to, algorithms, software, models, example applications, benchmarking, and innovative solutions such as Large Language Models for CAD.

Paper Submission

Abstract due:

May 16, 2025 (AOE)

Full manuscript due:

May 23, 2025 (AOE)

Notification: July 7, 2025

Camera-Ready Version:

July 25, 2025

Research Track (papers and presentations)

Paper submission: Submissions should be full-length papers of up to six pages (PDF format, double-column, US letter size, using the IEEE format). References and appendices are not included in the page limit. Submissions must be anonymous to allow a double-blind review process. Submitted papers must describe original work that has not been published/accepted and that is not currently under review.

Symposium proceedings: Formal shared ACM/IEEE proceedings will be published containing all accepted papers and will be available through both IEEE Xplore Digital Library and ACM Digital Library.

Artifact review and badging will be available for accepted papers.

Journal special issue: The symposium will collaborate with a major EDA journal for a special issue on MLCAD.

Industry Track (presentations only)

The industry track will provide a forum for sharing industrial experiences on ML applications in chip designs.

Abstract submission: An abstract of 300-500 words must be submitted by May 23, 2025. The first author and most co-authors must have industrial affiliations. **Notification:** June 27, 2025.

Slides submission: Presentation slides must be submitted for review by August 1, 2025.

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